

Ultra Clean Processing of Semiconductor Surfaces XI

von

Paul Mertens, Marc Meuris, Marc Heyns

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Table of Contents

Preface, Committees and Acknowledgements

Keynote

Silicon & beyond CMOS: The Path of Advanced Electronic Structure Engineering for Low-Voltage Transistors

A. Thean

3

Chapter 1: Cleaning for FEOL Applications

Cleaning Technology for Advanced Devices beyond 20 nm Node

Y. Ogawa

7

Dummy Oxide Removal in High-K Last Process Integration how to Avoid Silicon Corrosion Issue

F. Sebaai, A. Veloso, H. Takahashi, A. Pacco, M. Claes, M. Schaekers, S. de Gendt, P.W. Mertens and H. Struyf

13

Implanted Photoresist Remover for Advanced Nodes Including SiGe, Ge and High K-Metals

S. Braun, R. Vos, A. Klipp, M. Claes, C. Bittner, J. Albert, N. Horiguchi and H. Struyf

17

Development of a Integrated Dry/Wet Hybrid Cleaning System

J.S. Lee, G.M. Choi, J.N. Jung, D.D. Lee, G.Y. Hur, J.H. Lee, C.H. Chi and D.H. Gimm

21

New Chemical Vapor Delivery Systems for Surface Cleaning

D. Alvarez Jr., J. Spiegelman, E. Heinlein, C. Ramos, R.J. Holmes and Z. Shamsi

25

Removal of UV Cured Resin Using Hybrid Cleaning Method

M.S. Kim, B.K. Kang, J.K. Kim, B.K. Lee and J.G. Park

30

Chapter 2: Wet Etching

Selective Nickel Silicide Wet Etchback Chemistry for Low Temperature Anneal Process

T.Y. Siang, S.B. Meng, L.L. San, L. Huang, Z. Ismail and A. See

37

Wet Etching Behavior of Poly-Si in TMAH Solution

H. Takahashi, M. Otsuji, J. Snow, F. Sebaai, K. Arai, M. Sato and S. Nadahara

42

Novel Wet Etching of Silicon Nitride in a Single Wafer Spin Processor

B. Yu, S. Huang, M. Yeh, C.C. Chen, S.M. Jang, A. Ratkovich, D. Yang, J.M. Lauerhaas and J.W. Butterbaugh

46

Selective Nitride Etch by Using Fluorides in High Boiling Point Solvent

H.C. Wu, E.I. Cooper and H.K. Hsu

50

SiO₂ Etch Rate Modification by Ion Implantation

E. Bellandi and V. Soncini

55

Surface Preparations Impact on 248nm Deep UV Photo Resists Adhesion during a Wet Etch

M. Foucaud, P. Garnier, V. Joseph, E. Pargon, N. Rochat and R. Tiron

58

Chapter 3: Surface Chemistry and Functionalisation

Chemical Control of Surfaces: From Fundamental Understanding to Practical Application

M.A. Hines

65

Surface Preparation of Poly-Si Using Dry Cleaning for Minimizing Interfacial Resistance

C.K. Seong, T.S. Lim, J.G. Lee, J.I. Lee, K.J. Park, K.H. Kim and Y.G. Shin

71

A Comparative Study for the Backside Illumination (BSI) Technology Using Bonding Wafer Cleaning Process for Advanced CMOS Image Sensor

C.K. Jung, S.W. Joo, S.H. Jeong, S.W. Ryu, H.C. Lee, J.Y. Cho, G.W. Park, Y.J. Lee, Y.W. Cha and J.W. Han

75

Clean Process Mechanism of HKMG during N-PMOS Patterning A. Yeh, K.P. Wang, Z.J. Wang, C.C. Chien, T. Guo, M. Chan, C.L. Yang, J.Y. Wu, S.S.H. Tan, A. Kabansky, T. Su and J. Kao	79
Study of Highly Selective and Sensitive Microarray Structure Based on Hydrophilic/Hydrophobic SAMs (Self-Assembled Monolayers) J.H. Lee, S.H. Cho, H.W. Lim, S.W. Kim, A.A. Busnaina, H.Y. Lee and J.G. Park	82
Evaluation of CD Fluctuation on QC Monitor C.Y. Yen, M.C. Luo, K.B. Huang and T.C. Wang	86
<i>In Situ</i> Studies of III-V Surfaces and High-K Atomic Layer Deposition B. Brennan, S. McDonnell, D. Zhernokletov, H. Dong, C.L. Hinkle, J. Kim and R.M. Wallace	90
ALD Growth Behavior of High-K Nanolayers on Various Substrates Characterized by X- Ray Spectrometry in Gracing Incidence Geometry M. Müller, S. Sioncke, A. Delabie and B. Beckhoff	95
Cleaning of III-V Materials: Surface Chemistry Considerations D.H. van Dorp, D. Cuypers, S. Arnauts, P.W. Mertens and S. de Gendt	98

Chapter 4: Cleaning for BEOL and 3D Applications

Unique Size-Dependent Challenges for BEOL Cleans in the Patterning of Sub-20 nm Features K.J. Singh	103
The Risk of Pattern Collapse for Structures in Future Logic Devices M. Sankarapandian, B. Peethala, D. Canaperi, D. Peter, P. Engesser and H. Okorn-Schmidt	107
Determination of Surface Energy Characteristics of Plasma Processed Ultra Low-K Dielectrics for Optimized Wetting in Wet Chemical Plasma Etch Residue Removal N. Ahner, S. Zimmermann, M. Schaller and S.E. Schulz	110
Wet Removal of Post-Etch Residues by a Combination of UV Irradiation and a SC1 Process E. Kesters, Q.T. Le, I. Simms, K. Nafus, H. Struyf and S. de Gendt	114
Analysis of Oxidized Copper Surface and its Evolution F. Milanese, F. Pipia, S. Spadoni, S. Grasso, E. Ravizza, M. Pistoni and M. Alessandri	119
Introduction of a Dynamic Corrosion Inhibitor for Copper Interconnect Cleaning A. Otake, A. Kuroda, R. Luo and P.R. Bernatis	124
Removing W Polymer Residue from BEOL Structures Using DSP⁺ (Dilute Sulfuric- Peroxide-HF) Mixture – A Case Study H.H. Lee, M.S. Yun, H.W. Lee and J.G. Park	128
UV-Induced Modification of Fluorocarbon Polymer: Effect of Treatment Atmosphere and Aging on Dissolution in Organic Solvent Q.T. Le, E. Kesters, T. Conard, H. Struyf and S. de Gendt	132
One-Step Wet Clean Removal of Post-Etch Fluoropolymer Residues W.R. Gemmill, E. Kesters and Q.T. Le	136
Determination of Fluoride Concentration on Aluminum Bond Pads Using Liquid Phase Extraction Ion Chromatography R. Te Brake, D.M. Knotter and M. Leenders-van Hees	139
Selective High-Throughput TiN Etching Methods E.I. Cooper, R. Rajaram, M. Payne and S. Lippy	143
The Effect of Ar/H₂ Plasma Pretreatments on Porous K=2.0 Dielectrics for Pore Sealing by Self-Assembled Monolayers Deposition Y. Sun, J. Swerts, P. Verdonck, A. Maheshwari, J.L. Prado, S. de Feyter and S. Armini	146
Development of Integrated Wet Cleans for 3D-SIC Technologies S. Suhard, I. Simms, I. Brown, M. Shogo, K. Koji, M. Claes, T. Buisson, A. Jourdain, G. Beyer and S. de Gendt	150
Post Chemical Mechanical Polish Cleaning Chemistry for through Silicon via Process C. Shang, T. Maw and F. Coder	154

Chapter 5: Particles and Megasonic Cleaning

Acoustic Bubbles: Control and Interaction with Particles Adhered to a Solid Substrate R. Mettin, P.E. Frommhold, X. Xi, F. Cegla, H. Okorn-Schmidt, A. Lippert and F. Holsteyns	161
Single Bubble Cleaning and Vortex Flow F. Reuter, R. Mettin, A. Lippert, F. Holsteyns and H. Okorn-Schmidt	165
Acoustic Cavitation Behavior in Isopropyl Alcohol Added Cleaning Solution B.K. Kang, J.H. Jeong, M.S. Kim, H.S. Sohn, A.A. Busnaina and J.G. Park	169
Towards an Improved Megasonic Cleaning Process: Influence of Surface Tension on Bubble Activity in Acoustic Fields E. Camerotto, S. Brems, M. Hauptmann, J. Lurquin, H. Struyf, P.W. Mertens and S. de Gendt	173
Influence of Dissolved CO₂ on Bubble Activity in Pulsed Acoustic Fields S. Brems, M. Hauptmann, E. Camerotto, A. Pacco, H. Struyf, M.M. Heyns, P.W. Mertens, S. de Gendt and C. Gottschalk	177
Evaluation of Very Dilute Alkaline Solutions for Wafer Cleaning with Megasonic Irradiation J.H. Jeong, B.K. Kang, M.S. Kim, H.S. Sohn, A.A. Busnaina and J.G. Park	181
Removal of Fine Particle Using SAPS Technology and Functional Water D.H. Wang, Y. Ma, F.P. Chen, L.Z. Xie, X. Wang, X.Y. Zhang, J.Y. Lee, D.J. Kim, J.Y. Lee, P. Leem and G.M. Choi	185
Non Destructive Nanoparticle Removal from Submicron Structures Using Megasonic Cleaning P. Karimi, A.A. Busnaina, B.K. Kang and J.G. Park	191
Physical Cleaning Enhancement Using Advanced Spray with Uniform Droplet Control Y.H.C. Chien, M. Yeh, S. Ku, C.M. Yang, C.C. Chen, S.M. Jang, K. Izumoto, K. Sotoku, T. Tanaka, M. Sato, H. Shirakawa and M. Tanaka	195
CO₂-Dissolved Water Cleans for 2xnm-Node Silicon Devices in a Single Wafer Megasonic System C.G. Park and H.S. Sohn	198
Direct vs. Indirect Megasonic Tank Cleaning Systems; Uniformity, Cleaning Efficiency and Cost of Ownership J. Desagher, D. Dussault, M. Beck, R. Lillard and E. Liebscher	201
Development of a Near-Field Megasonic Cleaning System for Nano-Particle Removal H.S. Kim, Y.L. Lee and E.S. Lim	205
Megasonic Cleaning to Remove Nano-Dimensional Contaminants from Wafer Surfaces: An Analytical Study R. Nagarajan, S. Jain, M.A. Prabhudesai, A. Khanolkar, M.P. Reddy, M.S. Kumar, R. Vetrinmurugan, P. Sundin, S. Thottathil and M.J. Goodson	209
Frictional Analysis of PVA Brush for Post CMP Cleaning: Effects of Rotation Speed, Compression Distance, and Fluid Viscosity T. Fujiwara, T. Sanada, A. Fukunaga and H. Hiyama	213
A New Retention Method for Sub-10 nm Liquid Filtration Using Fluorescent CdSe QDs S.W. Liu and H.Z. Zhang	217

Chapter 6: Wetting and Drying

Investigation of the Evaporation and Wetting Mechanism of IPA-DIW Mixtures X.M. Xu, J. Smeers, G. Vereecke and H. Struyf	223
Effect of the Surface/Water Chemistry on the Creation of Watermarks N. Belmiloud, A.H. Tamaddon, P.W. Mertens and H. Struyf	227
Influence of Ammonia Gas Ambient in IPA Drying Process of the Single Wafer Cleaning System Y. Hagimoto, H. Iwamoto, Y. Kawabuchi and T. Minami	231
Wetting Challenges in Cleaning of High Aspect Ratio Nano-Structures X.M. Xu, G. Vereecke, E. van den Hoogen, J. Smeers, S. Armini, T. Delande and H. Struyf	235
Evaluation of High-Speed Linear Air-Knife Based Wafer Dryer A.H. Tamaddon, N. Belmiloud, G. Doumen, H. Struyf, P.W. Mertens and M.M. Heyns	239
Improved Drying Technology of Single Wafer Tool by Using Hot IPA/DIW C.H. Kim, M.S. Yun, T.H. Hwang, C.H. Nam, S.C. Kim, J.H. Roh, M.S. Lee and J.S. An	243

Effects of Substrate Temperature on the Leaning of Micropatterns during Rinse-Dry Process	
T.H. Kim, J.C. Kim, S.H. Kim and H.Y. Kim	247
Advanced Vacuum Wafer Drying for Thermal Laser Separation Dicing Assessment Results from European Collaborative “SEAL” Project	
O. Le Barillec, M. Davenet, A. Favre, B. Bellet, M. Koitzsch, D. Lewke, M. Schellenberger and H.U. Zühlke	252

Chapter 7: Metal Contamination

Diffusion Behavior of Transition Metals Penetrating Silicon Substrate through Silicon Dioxides by Dopant Ion Implantation	
K. Saga	261
Evaluation of Hafnium Contamination on Wafer Surfaces after the Wet Cleaning Process	
S. Saito, Y. Hagimoto and H. Iwamoto	265
Real-Time Analyses of Metal Contaminations in the ppb-Range	
A. Hutterer, M. Bauhuber, H. Hummel and A. Lechner	269
X-Ray Induced Depth Profiling of Ion Implantations into Various Semiconductor Materials	
P. Hönicke, M. Müller and B. Beckhoff	274
Characterization of Surface Metal Contaminations on Fused Quartz	
S. Liu and B. Liu	277

Chapter 8: Cleaning and Wet Etching for Silicon Photo-Voltaic Applications

Cleaning in Crystalline Si Solar Cell Manufacturing	
J. Schweckendiek, R. Hoyer, S. Patzig-Klein, F. Delahaye, G. Knoch and H. Nussbaumer	283
How to Overcome the Effects of Silicon Build-Up during Solar Cell Wet Chemical Processing	
I. Kashkoush, J. Rieker, G. Chen, D. Nemeth and A. Danel	289
'Just Clean Enough': Wet Cleaning for Solar Cell Manufacturing Applications	
K. Wostyn, W. Baekelant, J. Rip, M. Haslinger, K. Kenis, H. Struyf, M. Claes, P.W. Mertens and S. de Gendt	293
Optimized Wet Processes and PECVD for High-Efficiency Solar Cells	
I. Kashkoush, G. Chen, D. Nemeth and J. Rieker	297
Wet-Chemical Conditioning of H-Terminated Silicon Solar Cell Substrates Investigated by Surface Photovoltage Measurements	
H. Angermann, U. Stürzebecher, J. Kegel, C. Gottschalk, K. Wolke, A. Laades, E. Conrad, C. Klimm and B. Stegemann	301
Combined Ozone/HF/HCl Based Cleaning and Adjusted Emitter Etch-Back for Silicon Solar Cells	
A. Moldovan, K. Birman, J. Rentsch, M. Zimmer, T. Gitte and J. Fittkau	305
Wet Chemical Oxidation of Silicon Surfaces Prior to the Deposition of Al-PECVD $\text{AlO}_x/a\text{-SiN}_x$ Passivation Stacks for Silicon Solar Cells	
A. Laades, H. Angermann, H.P. Sperlich, U. Stürzebecher, C.A.D. Álvarez, M. Bähr and A. Lawrenz	310
Surface Charge and Interface State Density on Silicon Substrates after Ozone Based Wet-Chemical Oxidation and Hydrogen-Termination	
H. Angermann, K. Wolke, C. Gottschalk, A. Moldovan, M. Roczen, J. Fittkau, M. Zimmer and J. Rentsch	314
Aspects of Surface Conditioning for High-Efficient Hetero-Junction Silicon Solar Cells	
L. Breitenstein, K.U. Ritzau, M. Hermle and W. Warta	318
Improved Surface Cleaning by <i>In Situ</i> Hydrogen Plasma for Amorphous/Crystalline Silicon Heterojunction Solar Cells	
S.N. Granata, T. Bearda, F. Dross, I. Gordon, J. Poortmans and R.P. Mertens	321